

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	BRS	L1	125	(polish\$3 recipe) same ((wafer or substrate or semiconductor) with annular) same thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 22:35			
2	BRS	L3	19	(polish\$3 recipe) same ((wafer or substrate or semiconductor) with annular) same thickness same profile	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 22:49			
3	BRS	L2	52	1 and @pd<="20010831"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 22:36			
4	BRS	L4	4	3 and @pd<="20010831"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 22:50			
5	BRS	L5	0	(polish\$3 with recipe) same ((wafer or substrate or semiconductor) with annular) same thickness same profile	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 22:49			
6	BRS	L6	0	(polish\$3 with recipe) same ((wafer or substrate or semiconductor) with annular) same thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 22:49			
7	BRS	L7	0	(polish\$3 adj recipe) same ((wafer or substrate or semiconductor) with annular) same thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 22:50			
8	BRS	L9	4	8 and @pd<="20010831"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 22:50			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
9	BRS	L8	22	(polish\$3 adj recipe) same (wafer or substrate or semiconductor) same thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 23:01			
10	BRS	L10	4	"6350179"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 23:01			
11	BRS	L11	66	SHANMUGASUNDRAM-ARULKUMAR-P.IN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 23:12			
12	BRS	L12	187	SCHWARM- ALEXANDER-T.IN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 23:12			
13	BRS	L13	20	PRABHU-GOPALAKRISHNA-B.IN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 23:12			